

SOT1459-2

wafer level chip-scale package; 42 bumps; 3.13 x 2.46 x 0.5 mm (backside coating included)

12 May 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP42
Package style descriptive code	WLCSP (wafer level chip-size package)
Package style suffix code	NA (not applicable)
Mounting method type	S (surface mount)
Issue date	26-4-2016

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.1	-	3.13	3.16	mm
E	package width	2.43	-	2.46	2.49	mm
A	seated height	0.46	-	0.5	0.54	mm
A ₂	package height	0.275	-	0.3	0.325	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	42	-	



2. Package outline

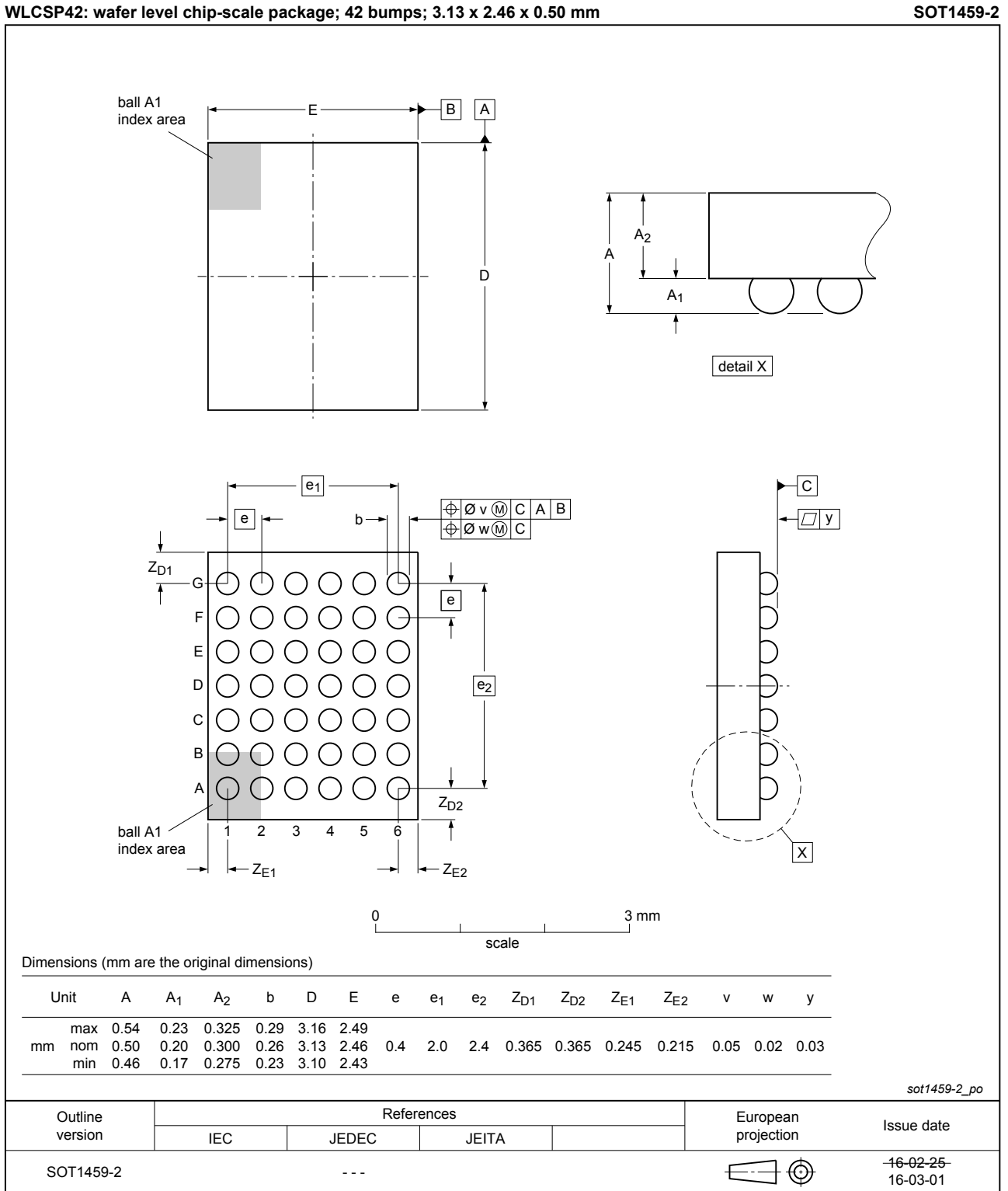


Fig. 1. Package outline WLCSP42 (SOT1459-2)

3. Legal information

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